

TEXT SEARCH  
EAST Search History

APPLICATION # 10564,856

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	5	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer) with (taper\$4 or slant\$4 or angle\$2)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 15:40
S2	8	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer) with (taper\$4 or slant\$4 or angle\$2)).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 10:43
S3	2	S1 and S2	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 10:44
S4	3	S1 not S3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 10:45
S5	6	S2 not (S1 or S3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 10:47
S6	249	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 10:46
S7	691	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer)).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 10:46

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S8	242	S6 not (S2 or S1 or S3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 11:05
S9	16	("4893404"   "5130179"   "5822856"   "6098282"   "6127633"   "6175087"   "6184477"   "6204453"   "6240636"   "6300576"   "6486394").PN. OR ("6828510").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/16 10:54
S10	19	("4943346"   "5263243"   "5567329"   "5651899").PN. OR ("5879568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/16 11:04
S11	640	S7 not (S6 or S2 or S1 or S3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 11:05
S12	178	((board or substrate) and (interlayer) and (insulat\$4) and (metal adj layer or conductive adj layer or copper adj layer) and (taper\$4 or slant\$4 or angle\$2) and (core) and (power) and (ground) and (via or hole or opening) and (thick\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 15:49
S13	5	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer) with (taper\$4 or slant\$4 or angle\$2)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 15:48
S14	8	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer) with (taper\$4 or slant\$4 or angle\$2)).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 15:48
S15	2	S13 and S14	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 15:48

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S16	249	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 15:48
S17	691	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer)).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 15:48
S18	640	S17 not (S16 or S14 or S13 or S15)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 15:48
S19	2196	((board or substrate) and (insulat\$4 or dielectric) and (metal adj layer or conductive adj layer or copper adj layer) and (taper\$4 or slant\$4 or angle\$2) and (core) and (power) and (ground) and (via or hole or opening) and (thick\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 15:50
S20	2018	S19 not (S12 or S18)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 15:51
S21	2017	S19 not (S12 or S18)	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/16 15:51
S22	1067	S19 not (S12 or S18)	USPAT; USOCR	OR	ON	2007/11/16 16:05
S35	178	((board or substrate) and (interlayer) and (insulat\$4) and (metal adj layer or conductive adj layer or copper adj layer) and (taper\$4 or slant\$4 or angle\$2) and (core) and (power) and (ground) and (via or hole or opening) and (thick\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 23:22

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S36	5	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer) with (taper\$4 or slant\$4 or angle\$2)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 23:22
S37	8	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer) with (taper\$4 or slant\$4 or angle\$2)).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 23:22
S38	2	S36 and S37	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 23:22
S39	249	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 23:22
S40	691	((board or substrate) with (interlayer) with (insulat\$4) with (metal adj layer or conductive adj layer or copper adj layer)).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 23:22
S41	640	S40 not (S39 or S37 or S36 or S38)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 23:22
S42	2196	((board or substrate) and (insulat\$4 or dielectric) and (metal adj layer or conductive adj layer or copper adj layer) and (taper\$4 or slant\$4 or angle\$2) and (core) and (power) and (ground) and (via or hole or opening) and (thick\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 23:22